



Docket No.: 240708US2

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

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RE: Application Serial No.: 10/625,583

Applicants: Kenichi HAYASHI, et al.

Filing Date: July 24, 2003

For: SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR ASSEMBLY MODULE

Group Art Unit: 2826

Examiner: WILLIAMS, ALEXANDER O.

SIR:

Attached hereto for filing are the following papers:

Request for Reconsideration under 37 C.F.R. § 1.111

Our check in the amount of -0- is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

A handwritten signature of Eckhard H. Kuesters.

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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

KENICHI HAYASHI, ET AL. : EXAMINER: WILLIAMS, ALEXANDER O.

SERIAL NO: 10/625,583 :

FILED: JULY 24, 2003 : GROUP ART UNIT: 2826

FOR: SEMICONDUCTOR DEVICE
AND SEMICONDUCTOR ASSEMBLY
MODULE

REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action dated April 12, 2007, please amend the above-identified application as follows:

Remarks begin on page 2 of this paper.